



## Discription

The ESDBM3V3A1 protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



DFN1006-2L  
(SOD-882)

## Features

- ★ Small Body Outline Dimensions
- ★ Low Body Height
- ★ Peak Power up to 105 Watts @ 8 x 20  $\mu$ s Pulse
- ★ Low Leakage current
- ★ Response Time is Typically < 1 ns
- ★ ESD Rating of Class 3 per Human Body Model



Circuit Diagram

## Ordering information

| Product ID | Pack                | Qty(PCS) |
|------------|---------------------|----------|
| ESDBM3V3A1 | DFN1006-2L(SOD-882) | 10000    |

## Absolute Ratings ( $T_{amb}=25^{\circ}\text{C}$ )

| Symbol           | Parameter                                                | Value        | Units |
|------------------|----------------------------------------------------------|--------------|-------|
| P <sub>pp</sub>  | Peak Pulse Power (t <sub>p</sub> = 8/20μ s)              | 100          | W     |
| T <sub>L</sub>   | Maximum lead temperature for soldering during 10s        | 260          | °C    |
| T <sub>stg</sub> | Storage Temperature Range                                | -55 to +150  | °C    |
| T <sub>op</sub>  | Operating Temperature Range                              | -55 to +150  | °C    |
| T <sub>j</sub>   | Maximum junction temperature                             | 150          | °C    |
|                  | IEC61000-4-2 (ESD)<br>air discharge<br>contact discharge | ± 30<br>± 30 | KV    |
|                  | IEC61000-4-4 (EFT)                                       | 40           | A     |



## Electrical Characteristics

| Device     | $V_{RWM}$<br>(V) | $I_R$ ( $\mu$ A)<br>@ $V_{RWM}$ | $V_{BR}$ (V) @ $I_T$<br>(Note 1) |     | $I_T$ | $V_C$ (V)<br>@ $I_{PP} = 1$ A<br>(Note 2) | $V_C$ (V)<br>@ MAX $I_{PP}$<br>(Note 2) | $I_{PP}$ (A)<br>(Note 2) | $P_{PK}$ (W)<br>(Note 2) | C (pF) | $R_{DYN}(\Omega)$<br>@ $t_p=100$<br>ns(TLP) |
|------------|------------------|---------------------------------|----------------------------------|-----|-------|-------------------------------------------|-----------------------------------------|--------------------------|--------------------------|--------|---------------------------------------------|
|            | Max              | Max                             | Min                              | Max | mA    | Max                                       | Max                                     | Max                      | Max                      | Typ.   | Typ.                                        |
| ESDBM3V3A1 | 3.3              | 0.05                            | 5                                | 6.5 | 1.0   | 7                                         | 11                                      | 99                       | 100                      | 15     | 0.2                                         |

- $V_{BR}$  is measured with a pulse test current  $I_T$  at an ambient temperature of 25°C.
- Surge current waveform per Figure 1.

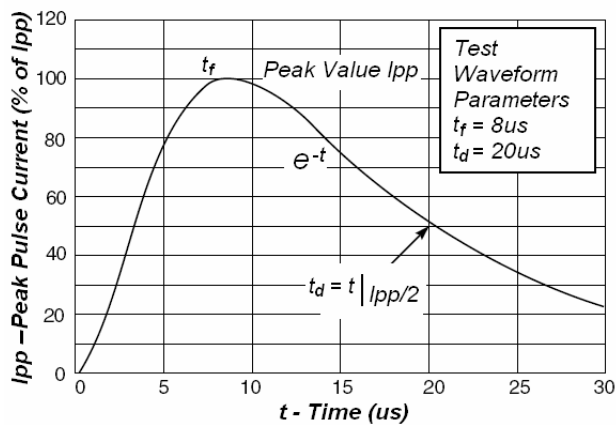


Fig1. Pulse Waveform

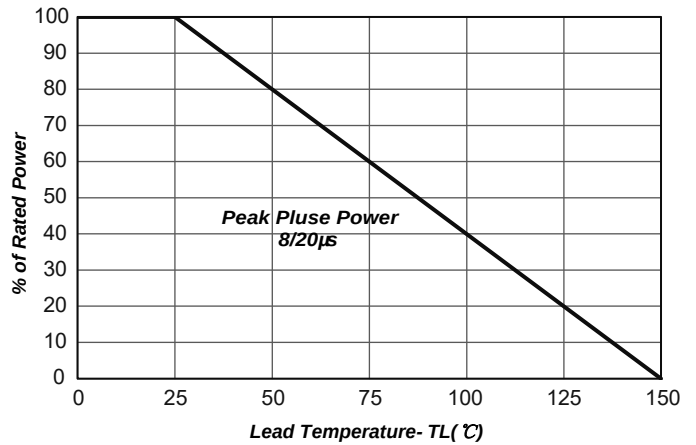


Fig2. Power Derating Curve

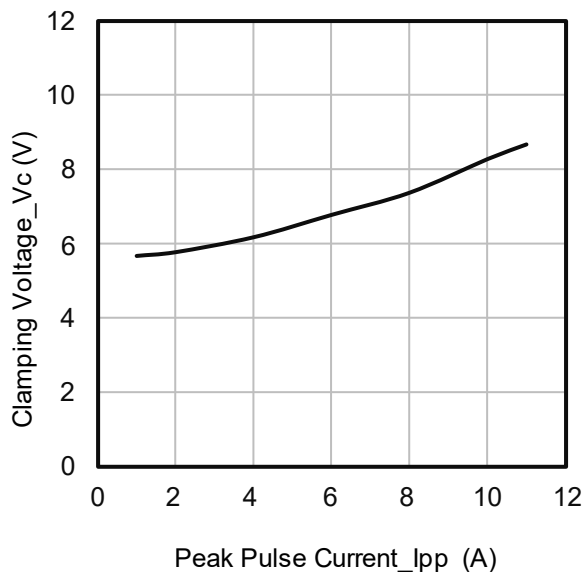


Fig3. Clamping Voltage vs. Peak Pulse Current

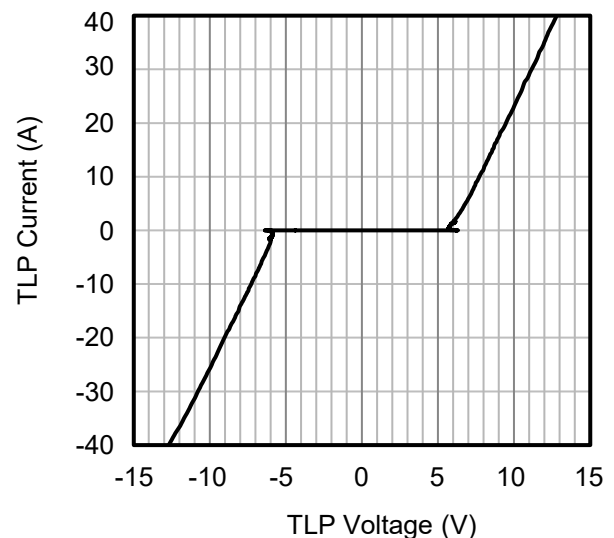
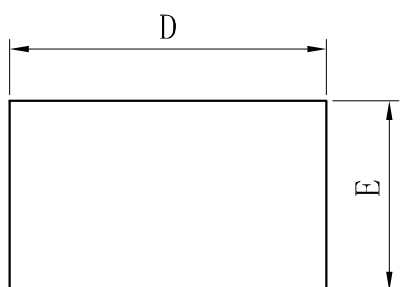


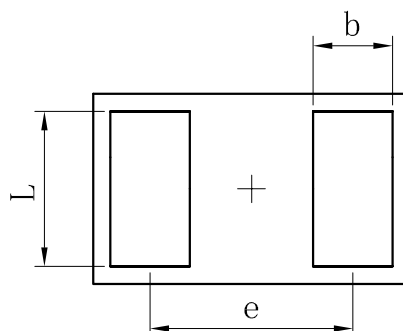
Fig4. TLP Measurement



## Outline And Dimensions

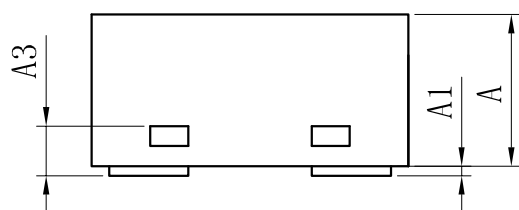


TOP VIEW



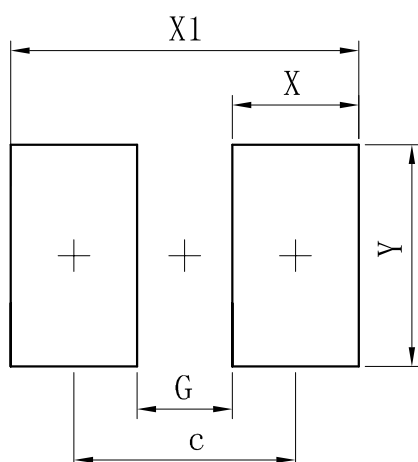
BOTTOM VIEW

| DFN1006-2L(SOD-882)  |           |      |      |
|----------------------|-----------|------|------|
| Dim                  | Min       | Typ  | Max  |
| D                    | 0.95      | 1.00 | 1.05 |
| E                    | 0.55      | 0.60 | 0.65 |
| e                    | —         | 0.64 | —    |
| L                    | 0.44      | 0.49 | 0.54 |
| b                    | 0.20      | 0.25 | 0.30 |
| A                    | 0.43      | 0.48 | 0.53 |
| A1                   | 0         | —    | 0.05 |
| A3                   | 0.127REF. |      |      |
| All Dimensions in mm |           |      |      |



SIDE VIEW

## Soledering Footprint



| Dimensions | (mm) |
|------------|------|
| c          | 0.70 |
| G          | 0.30 |
| X          | 0.40 |
| X1         | 1.10 |
| Y          | 0.70 |



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